IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information				
upplier	Information													
Company name* Company u				y unique ID			Unique ID Authority				Response Date*			
onsemi											2024-05-18			
ontact Na	ame	Title - Contact			I	Phone - Contact*				Email - Contact*				
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Product-Env-Stewards Product Enviro Complian				iro Compliance	liance		NA			Prod	Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Manufacturing S	ufacturing Site		UOM	Unit Type	
	MJL21195G BIP T0264 PNP		BIP T0264 PNP 10	6A 250V FG		2024-05-18 KR8			10737.244	mg	Each			
	cturing Process Informa		F 1 D	A.11	CTD 020 MC	U. Datina	De els Dese	D. L. T.	Mar Time of	Deale Transport	No.	and Deflect Court		
8		· · · · · · · · · · · · · · · · · · ·		-STD-020 MS	L Rating	Peak Process Body Temperature Max Time a  0 C 30			1.	<u> </u>				
	Matte Tin (Sn) - annealed		CU Alloy	N	(A		]0	IC.	30	sec	conds 3			
omments														
	nformation regarding materia													

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.004	mg	Supplier	Silicon (Si)	7440-21-3		0.004	mg
Die Attach	438.49	mg	A	Lead (Pb)	7439-92-1	7a	416.5655	mg
			Supplier	Tin (Sn)	7440-31-5		21.9245	mg
Lead Frame	6869.64	mg	Supplier	Zinc (Zn)	7440-66-6		6.8696	mg
			Supplier	Iron (Fe)	7439-89-6		6.8696	mg
			Supplier	Copper (Cu)	7440-50-8		6855.9009	mg
Mold Compound-Black	3393.27	mg		Brominated epoxy resin	proprietary data		135.7308	mg
			Supplier	Phenolic Resin	Proprietary Data		173.0568	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		44.1125	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2694.2566	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		346.1133	mg
Plating	34.3	mg	Supplier	Tin (Sn)	7440-31-5		34.3	mg
Wire Bond - Al	1.54	mg	Supplier	Aluminum (Al)	7429-90-5		1.54	mg